

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	2	@ad<="20040330" and "wiring substrate" same "solder ball" same "PCB"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:39
L4	1267	@ad<="20040330" and "wiring substrate" same ("solder ball" or "bump")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:39
L5	13	@ad<="20040330" and "wiring substrate" same ("bump") same "plug"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
L6	1032	@ad<="20040330" and "wiring substrate" same "bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
L8	1234	@ad<="20040330" and "wiring board" same "solder bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
L9	246	@ad<="20040330" and "wiring board" with "bump" same "copper"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:45
L10	101	@ad<="20040330" and "wiring circuit board" with "bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:50
L13	2	@ad<="20040330" and "wiring circuit board" and "plug" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51
L14	16	@ad<="20040330" and "wiring circuit board" and "metal" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51
L16	30	@ad<="20040330" and "wiring circuit board" and "bump" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51

EAST Search History

S1	2	"20040201096"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:03
S2	2289	@ad<="20040330" and (257/678). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:13
S3	2099	@ad<="20040330" and (257/697-698).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S4	1585	@ad<="20040330" and (257/700). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S5	1913	@ad<="20040330" and (257/784). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38
S6	1756	@ad<="20040330" and (257/786). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:07
S7	10	@ad<="20040330" and 'flexible' same 'wiring circuit' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S8	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:10
S9	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:11
S10	6144	@ad<="20040330" and (361/749-750).ccls. or (361/760). ccls. or (361/792).ccls. or (361/795).ccls. or (257/686).ccls. or (257/685).ccls. or (257/688).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S11	21	@ad<="20040330" and 'flexible' same 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:20
S12	864	S10 and 'flexible' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:17

EAST Search History

S13	235	@ad<="20040330" and 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:38
S14	1	"6285081".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30
S15	1	"6181569".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30
S16	1	"6114187".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S17	1	"6005292".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S18	1	"5900738".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S19	1	"5414371".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S20	1	"5086337".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S21	3938	@ad<="20040330" and (257/773-774).cccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38
S22	931	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
S23	6	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
S24	10	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
S25	8	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'plug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
S26	180	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:15

EAST Search History

S27	2	("6329610").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 10:56
S28	9	((("5811982") or ("5914614") or ("6329827") or ("6722032"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08
S29	1	"5177438".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
S30	1	"5576630".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
S31	4	((("6288905") or ("6376769"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08
S32	951	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16
S33	353	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16
S34	51	@ad<="20040330" and 'wiring substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S35	233	@ad<="20040330" and 'wiring board' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
S36	4	@ad<="20040330" and 'wiring tape' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
S37	0	@ad<="20040330" and 'fixibel' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25

EAST Search History

S38	0	@ad<="20040330" and 'fixibel' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S39	0	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26
S40	425	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
S41	6	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26
S42	105	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'bump' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:57
S43	5	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'stud' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
S44	1	"6010769".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:36
S45	1	"5876842".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
S46	1	"5744758".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
S47	1	"5600103".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
S48	1	"5510216".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
S49	67	@ad<="20040330" and 'tape' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
S50	2	("6081026").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 12:06
S51	1	"5854534".PN.	USPAT; USOCR	OR	ON	2005/10/20 12:09

EAST Search History

S52	96	@ad<="20040330" and 'flexible' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
S53	80	@ad<="20040330" and 'flexible' with 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12